

OXYGEN-FREE COPPER(OFC)

HITACHI

OXYGEN-FREE COPPER

Worlds Purest Form of ''Oxygen-Free'' Copper

The World's Top	Production
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Hitachi Cable has been producing various Copper products like Copper Tubings, Bars and Strips since its first successful mass production of Oxygen Free Copper (OFC) in Japan. Currently, in both aspects of quality and volume, Hitachi Cable is the top manufacturer of Oxygen Free Copper products in the world. From electronic components to a huge particle accelerator, Hitachi OFC and OFC based alloy are widely used all over the world.

State of the Art Total Quality Control

From casting ingots through to product shipping, Hitachi Cable maintains its criteria of quality control that is a "top-to-bottom" and an "all-in-one" process control in one factory. It keeps products' quality constantly high, and both the quantity and schedule of production as planned.

Hitachi Cable applies its own cast ingots for not only the pure Oxygen Free Copper products but also the OFC based alloy products, and maintains them at the highest quality.



Unique Process and Speciality Products

Hitachi Cable is the leading company of OFC manufacturing technology, and it developed the world's unique technique, the vacuum degassing process for continuous casting plant (US pat.). This technology effectively reduces the residual gases in Copper and ensures the high yield production of ASTM-F68 Class 1 certified grade Copper that includes the least contaminations in its grains and grain boundaries. Hitachi Class 1 grade OFC is identified as the top grade of Oxygen Free Copper with its extremely low gas content and is widely used for ultra high vacuum facilities like particle accelerators or semiconductor fabrications.

Hitachi Cable also provides the speciality Copper products like CG-OFC (Cryogenic OFC) for a wide range of applications. CG-OFC reduces the residual resistivity to half of the conventional OFC and it is the best material for superconductors.

Oxygen Free Copper Provides Advantages of Purity, Formability, Thermal Conductivity, etc.

Comparison with Other Coppers

Material			Oxygen Free Copper (OFC)		Phosphorous Deoxidized Copper (P-DCu)	Electrolytic Tough Pitch (ETP)	
CDA alloy No.		C10100 C10200		C12200	C11000		
Chomior		* 1 Cu(min)	99.99	99.96	99.90	99.90	
Requireme	ent	O2	0.0005	0.0010	NA	NA	
on ASTM B	152	(max)	(Typicall for Hitad	y 3ppm, chi OFC)	(Around 50 ppm)	(Around 400 ppm)	
(%)		Р	0.0003max	NA	0.015~0.040	NA	
Density	Ingot		8.90		8.90	8.4~8.6	
(g/cm ³) Form		rmed	8.94		8.94	8.89~8.94	
Gas Desorption in an Elevated Temperature		Extremely low		Vaporization of phosphorus	Relatively low		
lomogeneity of I	Micros	tructure	Excellent		Good	OK	
Electrical Conduct	yvity (S	% IACS)	102		82	101	
Thermal Conductyvity (W /m •K)		tyvity	391		339	381	
Resistance to Hydrog	en Emb	prittlement	Excellent		Good	Poor	
Deep-drawir	ng Q	uality	Excellent		Good	OK	
Oxide Scale	Adh	esion	Excellent		Poor	Good	
Softening Te	mper	ature	Slightly high		High	Low	
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*1: Including Silver

OFC Worldwide Specifications

	Natio	n	Japan		USA		UK		Germany
	Standard	d No.	JISH2123		ASTMB170		BS6017		DINI787
	ltem		Copper Billets and Cakes		Oxygen-Free Electrolytic Copper Refinery Shapes		Oxygen-Free Refined Coper		Oxygen-Free Coper without Deoxidizer
Material Opec.	0		Grade 1	Grade 2	Grade 1	Grade 2	Cu-OFE	Cu-OF	OF-Cu
	Classific	ation	C1011	C1020	C10100	C10200	C103	C110	2.0040
	Chemical Composition	*2 Cu (%min)	99.99	99.96	99.99	99.95	99.99	99.95	99.95
		O2 P (ppm)	10 max 3 max	10 max NA	5 max 3 max	10 max NA	10 max 3 max	NA NA	NA NA
Related Standards of Formed Copper Products		JIS H3510 Oxygen free copper sheet, plate, strip, seamless pipe and tube, rod, bar and wire for electron devices	JIS H3100 3140 3250 3300 Copper bus bars, rods and bars, seamless pipes and tubes	ASTM F68 Oxygen free copper in wrought forms for electron devices Class 1 Class 5	ASTUM B75 B152 B248 Tube, sheet, strip, plate and rolled bar	BS287 Tube, strip, pl rolle	0~2875 sheet, ate and d bar	DIN40500-Part4 Copper material for electrical use	

*2: Including silver

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Comparison of OFC, Stainless Steel and Aluminum

Material	Oxygen Free Copper (C10100)	Stainless Steel (SUS304)	Aluminum Alloy (A6063)
Density (g/cm ³)	8.94	8.03	2.71
Melting Point (°C)	1,083	1,425	630
lectrical Conductyvity (%IACS)	102	2	58
hermal Conductyvity (W /m • K)	391	16	201
lasticity Modulus (MPa)	118,000	193,000	69,000
ligidity Modulus (MPa)	44,000	72,000	26,000
ensile Strength (MPa)	220	680	140
Elongation (%)	45	55	25
ending Fatigue Strength (MPa)	162	785	107
efficient of Thermal Expansion (x10 ⁻⁶ /K)	17.0	17.3	23.0

SUS304 : Fe+18%Cr+8%Ni

A6063 : AI+0.7%Mg+0.4%Si

Hitachi OFC products meet all specifications above.

OXYGEN-FREE COPPER

Hitachi OFC Class1 and Other Specialty OFCs Meet Every Requirement.

Typical Properties of Hitachi OFC and OFC based

	Product Type	Trade Name [CDA No.]	Chemical* ¹ Composition [wt%]	Electrical* ² Conductivity [% IACS]	Softening* ³ Temperature [°C]	Advantage	Application
Oxygen Free Copper	OFC for Ultra High Vacuum	ASTM F68 Class1 [C10100, ASTM F68, Class 1]	Cu:>99.99	101	200	Least gas desorption Least contamination in microstructure	Accelerator cavities Electron tubes Transmission tubes Target material
	OFC for Cryogenic Use	CG-OFC [C10100]	Cu:>99.99	101	200	Extremely low residual electrical resistivity in cryogenic temperature	Stabilizer materials for superconductors
	OFC for Electron Devices	C10100 [C10100]	Cu:>99.99	101	200	Superb conductivity, weldability and formability Excellent scale adhesion	Vacuum circuit breakers, transmission tubes and magnetrons Target material
	OFC for General Use	C10200 [C10200]	Cu:>99.96	100	200	Superb conductivity, weldability and formability	Conductor of communication cables, heat sinks and for other general use
aring Oxygen Free Copper	Low	HCL-02Z [C15150]	Cu+Zr:>99.96 Zr:0.015~0.030	97	450	The highest heat resistance among dilute allovs. excellent	Lead frames for semiconductor devices
	Medium Zirconium	C151 [C15100]	Cu+Zr:>99.96 Zr:0.05~0.15	94	500	wire-bondability and resin adhesion	
Zirconium Be	High Zirconium	C150 [C15000]	Cu+Zr:>99.96 Zr:0.10~0.20	92	500	The highest heat resistance among dilute alloy Excellent fatigue strength	Electrode chips for welders
Tin Bearing Copper	Tin Bearing Oxygen Free	HCL-12S [C14415]	Cu+Sn:>99.96 Sn:0.10~0.15	90	350	Well-balanced electrical conductivity and heat resistance	Lead frames for semiconductor devices Radiator fins
ree Copper	Low Silver	3Ag-OFC [C10400]	Cu+Ag:>99.96 Ag:0.027~0.034	97	350		
ıg Oxygen Fr	Medium Silver	8Ag-OFC [C10700]	Cu+Ag:>99.96 Ag:0.085~0.102	97	360	Good abrasive resistance, electrical conductivity and heat resistance	Commutator bars Trolley wires
Silver Bear	High Silver	20Ag-OFC [—]	Cu+Ag:>99.96 Ag:0.15~0.25	97	360		

*1 : Specified range

*2, *3 : Typical value and may change according to material temper.

Hitachi OFC is Widely Used in Cutting-Edge Technology Field.



Particle Accelerator Cavities (courtesy of Fermi National Accelerator Lab.)



Lead Frames for Semiconductor Devices

Material Recommendation Chart

Requirement Electrical Thermal Mechanical Formability Low Gas Desorption Re Conductivity Conductivity Strenath Application Electron Tube for Particle Accelerator Vacuum Equipments [Magnetrons, Wave Guides, etc.] Stabilizer Materials for Superconductors Lead Frames for Semiconductor Devices Bus Bars, Bus Ducts Commutator Bars Hollow Conductors **Trolley Wires** Connectors [Pins, Sleeves] Conductors for Communication Cables Conductors for Sound Equipment Cables Chip Electrodes for Welders Target material =indispensable =requi

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Multi Gauge Copper Strips



Materials for Electron Devices

leat istance	Hydrogen Embrittlement Resistance	Corrosion Resistance	Solderability Brazability Weldability	Oxide Scale Adhesion	Abrasion Resistance	Recommended Material
						ASTM F68 Class1 C10100
						C10100
						CG-OFC C10100
				•		C151 HCL-02Z HCL-12S
						C10200
						Ag-OFC
						C10200
						Ag-OFC
						C10200
						C10200
						ASTM F68 Class1 C10100
						C150
						ASTM F68 Class1 C10100
ired						

Materials for Ultra High Vacuum Use C10100 ASTM F68 Class1

Accelerator Cavities (courtesy of Fermi National Accelerator Lab.)



Applications

Electronics

Components

Telecommunication

Infrastructures

High Energy Physics

Medical Instruments

Others

Available Shapes

customers' request.

Magnetrons

Electron Tubes

Magnetrons, back plates of sputtering

Microwave transmission tubes and

Accelerator cavities, wave guides,

CT scanner and laser components

Magnet wires and audio/video cables

Target material

vacuum circuit breakers

klystrons, and gaskets

Bars, Plates, Tubes and other custom shapes upon

300

apparatus and hearths for CVD systems.

Features

- Oxygen Free Copper (OFC) is the best material for electron tubes, wave guides and other vacuum equipments because of its superb electrical and thermal conductivity.
- · A Minimum-Risk of contaminations in microstructure ensures a leak tight operation.
- The vacuum degassed OFC that meets ASTM F68 Class1 is strongly recommended for its lowest gas desorption and highest discharge breakdown field.



Vacuum degassed

Microstructure improvement by vacuum degassing

Properties





ump

Holding





Discharge Breakdown in Vacuum



Features

- · Residual Resistivity Ratio (RRR) of CG-OFC is increased from 200-300 of conventional OFC to 500 or more by purifying with the vacuum degassing process.
- Other general properties meet ASTM B170 specification of Oxygen Free Copper Grade 1.

Properties

	CG-OFC	C1
Residual Resistivity Ratio (RRR)	500 min	200
Thermal Conductivity (W /m⋅K at 4.2K)	3,300 min	1,300



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Stabilizer for Superconductor / Thermal Conductor for Cryogenic Use C10100 CG-OFC



Nb₃Sn Superconductor

Applications

Stabilizer materials for superconductors, and thermal conductors for cooling astronomical CCD cameras or specimens in electron microscopes.

Available Shapes

Bars, Plates, Strips, Tubes and other custom shapes upon customers' request.

0100

0-300

00-2,000



Thermal Conductivity in Cryogenic Range

Power Distributor (Plates, Rods and Formed Bars)

C10200 C150 Ag-OFC



Machined Rods



Features

- Made of Oxygen Free Copper (OFC) for its superb electrical and thermal conductivity. OFC based silver or zirconium bearing alloy also available.
- Various shapes including plates, rods and formed bars are available.
- Superb formability at a room temperature and brazability in a hydrogen atmosphere.
- Bent, stamped or machined products are available for order.

Applications

Plates : heat sinks, bus bars for power distributors, switchbars, end rings of motors.

Rods : terminals, base plates for thyrister, electrodes.

Formed bars : connectors, trolley wires, commutator bars.

Available Dimensions

Plates : thickness=3mm min, width=530mm max (In some conditions, thickness less than 3mm is available)

Rods : from 4 to 100mm diameter (Larger diameter is available by forging)

Formed bars : ask for desirable shapes.





Isochronal Annealing Curves of OFC and Zr Bearing OFC



Bending Fatigue Curves of OFC and Zr Bearing OFC

Features

- Hitachi OFC certifies excellent electrical and thermal conductivity, and its superb formability provides the production of seamless hollow conductors by drawing.
- · Seamless tube also ensures no water leakage.
- High purity provides superb weldability or solderablity, and maintains high corrosion resistance.

Application

Water cooling coils for induction furnaces, generators, magnets of particle accelerators or plasma research equipments and other heavy duty power loads.

Standard Grade and Temper					
Standard Grade	C10200				
Temper	О, 1/2Н, Н				

Please refer to our exclusive brochure for standard shapes and dimensions. The examples of cross sectional shapes are shown on the right.

OXYGEN-FREE COPPER

Power Distributor (Hollow Conductors)

Hollow Conductors



Examples of Cross Sectional Shapes

Commutator Bars

Ag-OFC

Features

Applications

Trolley wires and commutator bars.

Molded Commutator Bars

- · Silver is the additive element to improve the heat resistance of OFC without significant degradation of electrical conductivity.
- Silver bearing OFC prevents itself from abrasion by brush owing to its high heat resistance during assembly and use.

Specification

	Chemical Composition [wt %]	Temper	Tensile Strength [MPa]	Vickers Hardness [Hv]	Electrical Conductivity [% IACS]	Softening Temperature [°C]
3Ag-OFC	Cu+Ag:>99.96, Ag:0.027 - 0.034	н	340	105	97	350
8Ag-OFC	Cu+Ag:>99.96, Ag:0.085 - 0.102	н	340	105	97	360
20Ag-OFC	Cu+Ag:>99.96, Ag:0.15-0.25	н	340	105	97	360

Properties





Isothermal Annealing Curves of OFC and Silver Bearing OFC

Process Flow and Quality Assurance System







